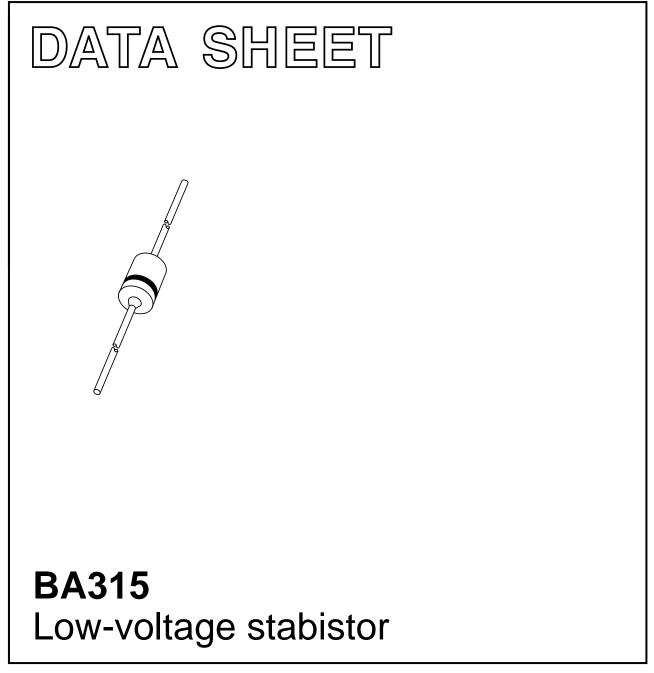
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of April 1992 File under Discrete Semiconductors, SC01 1996 Mar 21



BA315

FEATURES

- Low-voltage stabilization
- Forward voltage range: 480 mV to 1050 mV
- Total power dissipation: max. 350 mW.

APPLICATIONS

- Low-voltage stabilization e.g.
 - Bias stabilizer in class-B output stages
 - Clipping
 - Clamping
 - Meter protection.

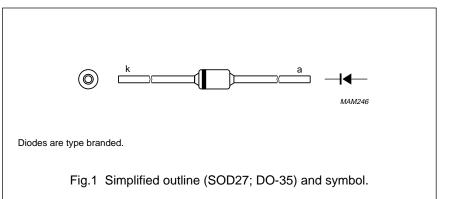
LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
|------------------|----------------------------|--------------------------|------|------|------|
| V _R | continuous reverse voltage | | _ | 5 | V |
| I _F | continuous forward current | | _ | 100 | mA |
| P _{tot} | total power dissipation | T _{amb} = 25 °C | _ | 350 | mW |
| T _{stg} | storage temperature | | -65 | +200 | °C |
| Tj | junction temperature | | _ | 200 | °C |

DESCRIPTION

Low-voltage stabilization diode in a hermetically-sealed SOD27 (DO-35) glass package.



BA315

ELECTRICAL CHARACTERISTICS

 $T_j = 25 \ ^{\circ}C$ unless otherwise specified.

| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|------------------|-------------------------|-----------------------------------|------|------|------|------|
| V _F | forward voltage | see Fig.2 | | | | |
| | | I _F = 0.1 mA | 480 | _ | 540 | mV |
| | | I _F = 1 mA | 590 | _ | 660 | mV |
| | | I _F = 5 mA | 670 | _ | 740 | mV |
| | | I _F = 10 mA | 710 | _ | 790 | mV |
| | | I _F = 100 mA | 875 | _ | 1050 | mV |
| I _R | reverse current | V _R = 5 V | _ | _ | 1500 | nA |
| r _{dif} | differential resistance | I _F = 1 mA; f = 1 kHz | _ | 50 | _ | Ω |
| | | I _F = 10 mA; f = 1 kHz | _ | 6 | 7 | Ω |
| S _F | temperature coefficient | I _F = 1 mA | _ | -2.1 | _ | mV/K |
| C _d | diode capacitance | V _R = 0 V; f = 1 MHz | - | _ | 3 | pF |

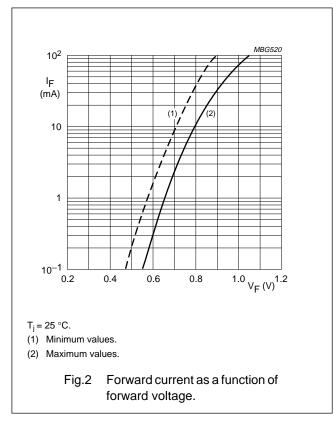
THERMAL CHARACTERISTICS

| SYMBOL | PARAMETER | CONDITIONS | VALUE | UNIT |
|----------------------|---|---------------------|-------|------|
| R _{th j-tp} | thermal resistance from junction to tie-point | 8 mm from the body | 300 | K/W |
| R _{th j-a} | thermal resistance from junction to ambient | maximum lead length | 600 | K/W |

Product specification

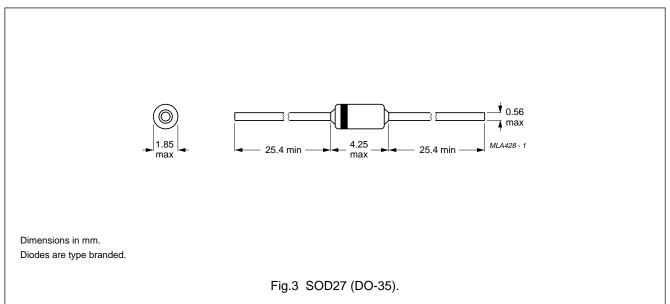
BA315

GRAPHICAL DATA



BA315

PACKAGE OUTLINE



DEFINITIONS

| Data sheet status | | |
|---|--|--|
| Objective specification | fication This data sheet contains target or goal specifications for product development. | |
| Preliminary specification | This data sheet contains preliminary data; supplementary data may be published later. | |
| Product specification | This data sheet contains final product specifications. | |
| Limiting values | | |
| Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability. | | |
| Application information | | |
| Where application information is given, it is advisory and does not form part of the specification. | | |

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.